MN3112SA

Vertical Driver for Video-Camera CCD Area-Image-Sensor

Overview

The MN3112SA is a vertical driver LSI incorporating four vertical driver channels and one sub driver channel for a 2-dimensional interline CCD image sensor.

The MN3112SA enables low current dissipation and the part reductions.

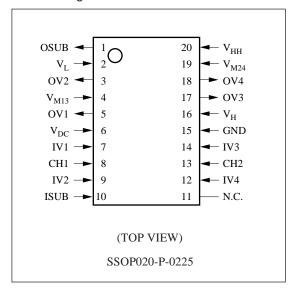
Features

• 3V power supply for input section

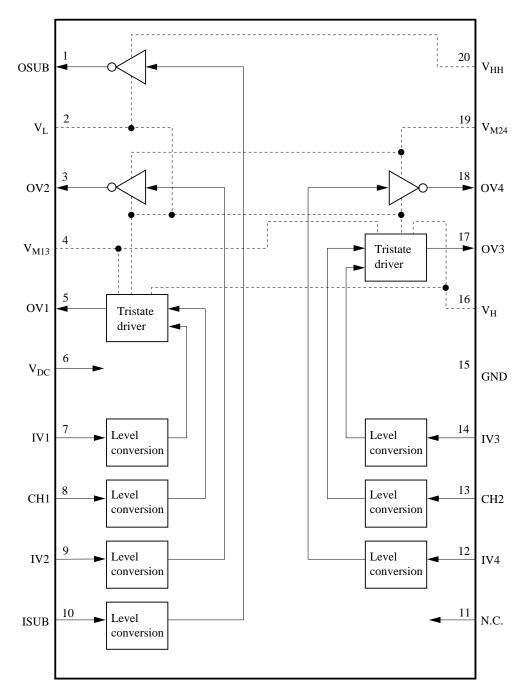
Applications

• Video cameras

■ Pin Assignment



■ Block Diagram



 V_{DC} , V_{L} , GND : Common power supply

 V_{M13}, V_{M24} : Binary and tristate independent power supplies for vertical driver section V_{HH}, V_{H} : Independent power supplies for sub driver section and vertical driver section

■ Pin Descriptions

Pin No.	Symbol	ymbol Pin Name		Function Description		
6	V _{DC}	Input section high-level power supply	I	5V high-level input		
15	GND	Input section low-level power supply	I	5V low-level input		
16	V _H	Vertical driver section high-level power supply	I	High-level input at high-voltage section		
20	V _{HH}	SUB driver section high-level power supply	I	High-level input at high-voltage section		
4 19	V _{M13} V _{M24}	Middle-level power supply	I	$\label{eq:middle-level} \begin{tabular}{ll} Middle-level input at high-voltage section \\ Input externally to both V_{M13} and V_{M24}. \end{tabular}$		
2	$V_{\rm L}$	Low-level power supply	I	Low-level input at high-voltage section		
9	IV2	Transfer pulse input	I	Charge transfer pulse input pin		
12	IV4	Transfer pulse input	I	Charge transfer pulse input pin		
7	IV1	Transfer pulse input	I	Charge transfer pulse input pin		
14	IV3	Transfer pulse input	I	Charge transfer pulse input pin		
8	CH1	Charge pulse input	I	Charge read pulse input pin		
13	CH1	Charge pulse input	I	Charge read pulse input pin		
10	ISUB	SUB pulse input	I	Unwanted charge sourcing pulse input pin		
18	OV4	Binary transfer pulse output	0	Binary transfer pulse output pin (V_{M24}, V_L)		
3	OV2	Binary transfer pulse output	0	Binary transfer pulse output pin (V_{M24}, V_L)		
17	OV3	Tristate transfer pulse output	О	Tristate transfer pulse output pin (V_H, V_{M13}, V_L)		
5	OV1	Tristate transfer pulse output	О	Tristate transfer pulse output pin (V_H, V_{M13}, V_L)		
1	OSUB	SUB pulse output	О	Unwanted charge sourcing pulse output pir (V_{HH}, V_L)		
11	N.C.	No connection	_			

■ Functions

Binary transfer pulse (vertical driver section)

IV2	OV2
IV4	OV4
Н	L
L	M

Tristate transfer pulse (vertical driver section)

CH1	IV1	OV1		
CH2	IV3	OV3		
11	Н	L		
Н	L	M		
Ī	Н	L		
L	L	Н		

^{*1} IV1, IV2, IV3, IV4, CH1, CH2

 $H: V_{DC}$

L: GND

OV1, OV2, OV3, OV4

 $H: V_H$

M: V_{M13} or V_{M24}

L: V_L

Unwanted charge sourcing pulse (SUB driver section)

ISUB	OSUB		
Н	L		
L	Н		

^{*1} ISUB

H: V_{DC}

L: GND

OSUB

 $H: V_{HH}$

 $L{:}\ V_L$

■ Electrical Characteristics

(1) DC characteristics

 $V_{HH}\!\!=\!18.0V\;,\;V_{H}\!\!=\!13.0V\;,\;V_{M13}\!\!=\!V_{M24}\!\!=\!1.0V\;,\;V_{L}\!\!=\!-7.0V,$

 $V_{DC}\!\!=\!\!5.00V$, GND=0.0V , Ta= $-10^{\circ}C$ to $+70^{\circ}C$

Parameter	Symbol	Test Conditions	min	typ	max	Unit
Quiescent supply current	I_{DDST}	V_I =GND , V_{DC} =3.0V			2.5	mA
		V _I =GND , V _{DC} =5.0V			4	IIIA
Operating supply current	I_{DDDYN}	V _I =GND , V _{DC}			7	mA
Input pins IV1, IV2, IV3,		1, CH2, ISUB				
Voltage "H" level	V _{IH}		$0.7 \times V_{DC}$		V _{DC}	V
Voltage "L" level	V _{IL}		GND		$0.3 \times V_{DC}$	V
Input leakage current	I_{LI}	V _I =0 to 5V			±1	μΑ
Output pins 1 (binary output)	OV2	, OV4				
Output voltage middle level	V _{OM1}	$I_{OM1} = -1 \text{mA}$	0.9		V _{M24}	V
Output voltage "L" level	V _{OL1}	I _{OL1} =1mA	$V_{\rm L}$		_	V
Output on-resistance middle level	R _{ONM1}	I _{OM1} =-50mA			40	Ω
Output on-resistance "L" level	R _{ONL1}	I _{OL1} =50mA			40	Ω
Output pins 2 (tristate output)	OV1	, OV3				
Output voltage "H" level	V _{OH2}	I _{OH2} =-1mA	12.9		V _H	V
Output voltage middle level	V _{OM2}	I _{OM2} =-1mA	0.9		V _{M13}	V
Output voltage "L" level	V _{OL2}	I _{OL2} =1mA	$V_{\rm L}$		_	V
Output on-resistance "H" level	R _{ONH2}	I _{OH2} =-50mA			50	Ω
Output on-resistance middle level	R _{ONM2}	I _{OM2} =±50mA			40	Ω
Output on-resistance "L" level	R _{ONL2}	I _{OL2} =50mA			40	Ω
Output pin 3 (SUB output)	OSUB					
Output voltage "H" level	V _{OHH3}	I _{OHH3} =-1mA	17.9		V _{HH}	V
Output voltage "L" level	V_{OL3}	I _{OL3} =1mA	$V_{\rm L}$		_	V
Output on-resistance middle level	R _{ONHH3}	I _{ONHH3} =-50mA			50	Ω
Output on-resistance "L" level	R _{ONL3}	I _{ONL3} =50mA			40	Ω

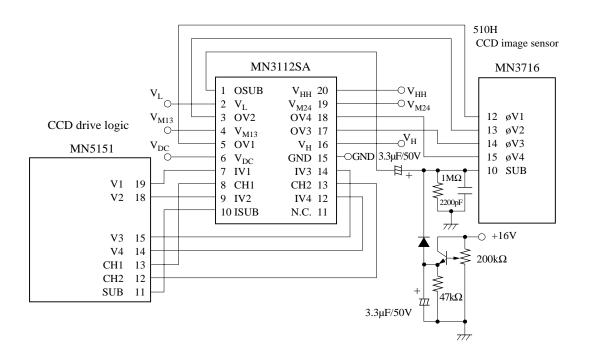
(2) AC characteristics

 $V_{HH}\!\!=\!\!18.0V\;,\,V_{H}\!\!=\!\!13.0V\;,\,V_{M13}\!\!=\!\!V_{M24}\!\!=\!\!1.0V\;,\,V_{L}\!\!=\!\!-7.0V,$

 $V_{DC}\!\!=\!\!3.0V$, GND=0.0V , Ta=–10°C to +70°C

Parameter	Symbol	Test Conditions	min	typ	max	Unit
Output pins 1 (binary output)	OV2	, OV4				
Transmission delay time	t _{PLM}	No load		100	200	ne
	t _{PML}	"L" level — middle level		100	200	ns
Rise time	t_{TLM}			200	300	ns
Fall time	t _{TML}			200	300	113
Output pins 2 (tristate output	OV1	, OV3				
Transmission delay time	t _{PLM}	No load		100	200	
	t _{PML}	"L" level — middle level		100	200	ns
Transmission delay time	t _{TMH}	No load		200	400	ne
	t _{THM}	middle level — "H" level		200	400	ns
Rise time	t_{TLM}			200	300	ne
Fall time	t _{TML}			200	300	ns
Rise time	t _{TMH}			200	300	
Fall time	t _{THM}			200	300	ns
Output pin 3 (SUB output)	OSUB					
Transmission delay time	t _{PLHH}	No load		100	200	
	t _{PHHL}	"L" level — "H" level		100	200	ns
Rise time	t _{TLHH}			200	300	ne
Fall time	t _{THHL}			200	300	ns

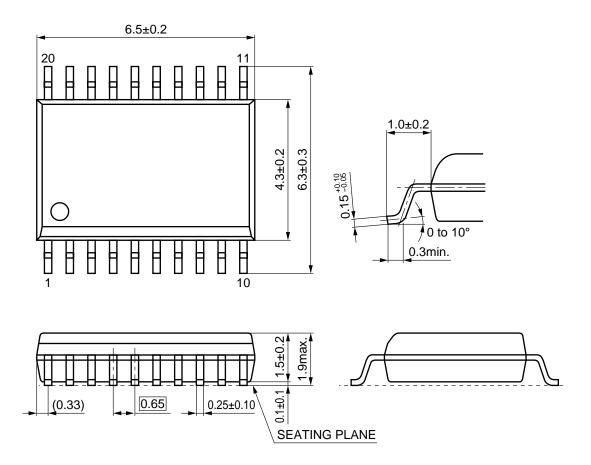
■ Application Circuit Example



Note *1: Connect a bypass capacitor as close as possible to each of the MN3112SA's power supply pins (V_{HH} , V_{H} , V_{M13} , V_{M24} , V_{L} , V_{DC}).

■ Package Dimensions (Unit: mm)

SSOP020-P-0225



Usage Notes

- (1) When the sub driver is not used
 - 1. Connect V_{HH} (pin 20) to V_H (pin 16).
 - 2. Connect ISUB (pin 10) to V_{DC} (pin 6) or GND (pin 15).
 - 3. Make no connection for OSUB (pin 1).
- (2) Connect a bypass capacitor as close as possible to MN3112SA power supply pins V_{HH} (pin 20), V_{H} (pin 16), V_{M13} (pin 4), V_{M24} (pin 19), V_{L} (pin 2), and V_{DC} (pin 6).
- (3) Guarantee period after unsealing
 - The guarantee period after opening the dry-sealed packaging is three weeks under the environment conditions of 30°C/70% (temperature/humidity).
- (4) The recommended reflow temperature is 230°C.

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